

DIODE ARRAY CIRCUITS

DESCRIPTION

The SG6100/SG6511 and SG6101/SG6510 diode arrays are monolithic, high breakdown, fast switching speed diode arrays. The SG6100/SG6511 is configured with 7 straight through diodes, while the SG6101/SG6510 has 8 straight through diodes.

These two diode array configurations allow the designer maximum flexibility for circuit design and board layout. Since each diode within the array has individual anode and cathode connections the device may be used in a variety of applications. Also, due to the array's monolithic construction the diode electrical parameters are very closely matched.

Both devices are available in ceramic DIP and flatpack and can be processed to Linfinty's S level, JANTXV, JANTX, or JAN equivalent flows.

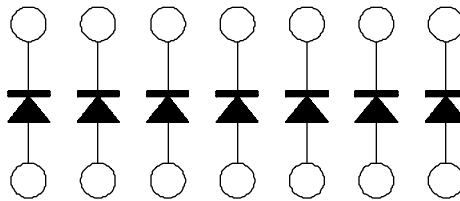
FEATURES

- 75V minimum breakdown voltage
- 100mA current capability per diode
- Switching speeds less than 5ns
- Low leakage current < 25nA

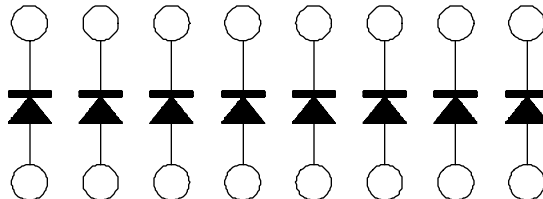
HIGH RELIABILITY FEATURES

- ◆ MIL-S-19500/474 QPL - 1N6100
- 1N6101
- 1N6510
- 1N6511
- ◆ Equivalent JANS, JANTXV, JANTX, JAN screening available

CIRCUIT DIAGRAMS



7 - STRAIGHT THROUGH DIODES
SG6100/SG6511



8 - STRAIGHT THROUGH DIODES
SG6101/SG6510

DIODE ARRAY SERIES

ABSOLUTE MAXIMUM RATINGS (Note 1 & 2)

Breakdown Voltage (V_{BR}) 75V
 Output Current (I_O), $T_C = 25^\circ\text{C}$
 Continuous 300mA

Note 1. Exceeding these ratings could cause damage to the device.
 Note 2. Applicable for each diode.

Operating Junction Temperature

Hermetic (J, F Packages) 150°C
 Storage Temperature Range -65°C to 200°C
 Lead Temperature (Soldering, 10 seconds) 300°C

THERMAL DATA

J Package (14 & 16 Pin):

Thermal Resistance-Junction to Case, θ_{JC} 30°C/W
 Thermal Resistance-Junction to Ambient, θ_{JA} 80°C/W

F Package (14 Pin):

Thermal Resistance-Junction to Case, θ_{JC} 80°C/W
 Thermal Resistance-Junction to Ambient, θ_{JA} 140°C/W

F Package (16 Pin):

Thermal Resistance-Junction to Case, θ_{JC} 70°C/W
 Thermal Resistance-Junction to Ambient, θ_{JA} 115°C/W

Note A. Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$.

Note B. The above numbers for θ_{JC} are maximums for the limiting thermal resistance of the package in a standard mounting configuration. The θ_{JA} numbers are meant to be guidelines for the thermal performance of the device/pc-board system. All of the above assume no ambient airflow.

RECOMMENDED OPERATING CONDITIONS (Note 3)

Operating Ambient Temperature Range

SG6100 -55°C to 150°C
 SG6101 -55°C to 150°C

SG6511 -55°C to 150°C
 SG6510 -55°C to 150°C

Note 3. Range over which the device is functional.

ELECTRICAL CHARACTERISTICS

(Unless otherwise specified, these specifications apply for the operating ambient temperature of $T_A = 25^\circ\text{C}$ for each diode. Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.)

| Parameter | Test Conditions | SG6100/SG6511 SG6010/SG6510 | | | Units |
|------------------------------------|--|--------------------------------|------|------|---------------|
| | | Min. | Typ. | Max. | |
| Breakdown Voltage (V_{BR}) | $I_R = 5\mu\text{A}$, Duty Cycle < 20% | 75 | | | V |
| Forward Voltage (V_F) | Duty Cycle $\leq 2\%$, 300 μs pulse $I_F = 100\text{mA}$ | | | 1.0 | V |
| Reverse Current (I_R) | $I_F = 10\text{mA}$, $T_A = -55^\circ\text{C}$ | | | 1.0 | V |
| | $V_R = 20\text{V}$ | | | 25 | nA |
| | $V_R = 40\text{V}$ | | | 100 | nA |
| Capacitance (C) (Note 4) | $V_R = 40\text{V}$, $T_A = 150^\circ\text{C}$ $V_R = 0\text{V}$, $f = 1\text{MHz}$, Pin-to-pin | | | 50 | μA |
| | | | | 4 | pf |
| Forward Recovery Time (t_{fr}) | $I_F = 500\text{mA}$, $t_r \leq 15\text{ns}$, $V_{fr} = 1.8\text{V}$, $R_S = 50\Omega$ | | | 15 | ns |
| (Note 4) | | | | | |
| Reverse Recovery Time (t_{rr}) | $I_F = I_R = 200\text{mA}$, $i_{rr} = 20\text{mA}$, $R_L = 100\Omega$ | | | 5 | ns |
| (Note 4) | | | | | |

Note 4. The parameters, although guaranteed, are not 100% tested in production.

DIODE ARRAY SERIES

CONNECTION DIAGRAMS & ORDERING INFORMATION (continued)

| Package | Part No. | Ambient Temperature Range | Connection Diagram |
|--|---------------------|---------------------------|--------------------|
| 14-PIN CERAMIC DIP J - PACKAGE | SG6511J (1N6511) | -55°C to 150°C | |
| 16-PIN CERAMIC DIP J - PACKAGE | SG6101J (1N6101) | -55°C to 150°C | |
| 14-PIN CERAMIC FLATPACK F - PACKAGE | SG6100F (1N6100) | -55°C to 150°C | |
| 16-PIN CERAMIC FLATPACK F - PACKAGE | SG6510F (1N6510) | -55°C to 150°C | |

Note 1. Consult factory for other packages available.
 2. All packages are viewed from the top.
 3. Consult factory for JAN, JANTX, JANTXV product availability.